

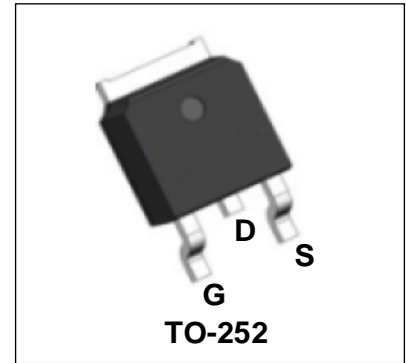
## 30V N-Channel Enhancement Mode Power MOSFET

### Description

WMO96N03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

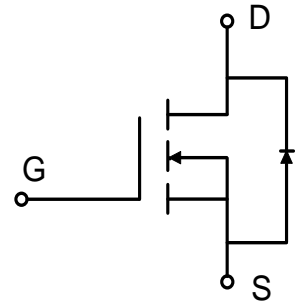
### Features

- $V_{DS} = 30\text{ V}$ ,  $I_D = 96\text{ A}$   
 $R_{DS(on)} < 4\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(on)} < 6\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



### Applications

- Power Management Switches
- BMS Protection
- Synchronous Buck Converter



### Absolute Maximum Ratings

| Parameter  | Symbol         | Value                     | Unit             |
|--|----------------|---------------------------|------------------|
| Drain-Source Voltage                             | $V_{DS}$       | 30                        | V                |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$                  | V                |
| Continuous Drain Current@10V <sup>1</sup>        | $I_D$          | $T_C = 25^\circ\text{C}$  | 96               |
|  |                | $T_C = 100^\circ\text{C}$ | 68               |
|  |                | $T_A = 25^\circ\text{C}$  | 19               |
|  |                | $T_A = 70^\circ\text{C}$  | 16               |
| Pulsed Drain Current <sup>2</sup>                | $I_{DM}$       | 192                       | A                |
| Single Pulse Avalanche Energy <sup>3</sup>       | <b>EAS</b>     | 144.7                     | mJ               |
| Avalanche Current                                | $I_{AS}$       | 53.8                      | A                |
| Total Power Dissipation <sup>4</sup>             | $P_D$          | $T_C = 25^\circ\text{C}$  | 62.5             |
|  |                | $T_A = 25^\circ\text{C}$  | 2.42             |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 to 175                | $^\circ\text{C}$ |

### Thermal Characteristics

| Parameter  | Symbol          | Value | Unit               |
|--|-----------------|-------|--------------------|
| Thermal Resistance from Junction-to-Ambient <sup>1</sup> | $R_{\theta JA}$ | 62    | $^\circ\text{C/W}$ |
| Thermal Resistance from Junction-to-Case <sup>1</sup>    | $R_{\theta JC}$ | 2.4   | $^\circ\text{C/W}$ |

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

| Parameter                                      | Symbol        | Test Conditions  | Min.                     | Typ. | Max.      | Unit       |         |
|--|---------------|--|--------------------------|------|-----------|------------|---------|
| <b>Static Characteristics</b>                  |               |  |                          |      |           |            |         |
| Drain-Source Breakdown Voltage                 | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$                            | 30                       | -    | -         | V          |         |
| Gate-body Leakage current                      | $I_{GSS}$     | $V_{DS} = 0V, V_{GS} = \pm 20V$                          | -                        | -    | $\pm 100$ | nA         |         |
| Zero Gate Voltage Drain Current                | $I_{DSS}$     | $V_{DS} = 24V, V_{GS} = 0V$                              | $T_J = 25^\circ\text{C}$ | -    | -         | 1          | $\mu A$ |
|  |               |  | $T_J = 55^\circ\text{C}$ | -    | -         | 5          |         |
| Gate-Threshold Voltage                         | $V_{GS(th)}$  | $V_{DS} = V_{GS}, I_D = 250\mu A$                        | 1.0                      | 1.7  | 2.5       | V          |         |
| Drain-Source On-Resistance <sup>2</sup>        | $R_{DS(on)}$  | $V_{GS} = 10V, I_D = 30A$                                | -                        | 3.4  | 4         | m $\Omega$ |         |
|  |               | $V_{GS} = 4.5V, I_D = 15A$                               | -                        | 4.5  | 6         |            |         |
| Forward Transconductance                       | $g_{fs}$      | $V_{DS} = 5V, I_D = 30A$                                 | -                        | 26   | -         | S          |         |
| <b>Dynamic Characteristics</b>                 |               |  |                          |      |           |            |         |
| Input Capacitance                              | $C_{iss}$     | $V_{DS} = 15V, V_{GS} = 0V, f = 1\text{MHz}$             | -                        | 3000 | -         | pF         |         |
| Output Capacitance                             | $C_{oss}$     |  | -                        | 410  | -         |            |         |
| Reverse Transfer Capacitance                   | $C_{rss}$     |  | -                        | 285  | -         |            |         |
| <b>Switching Characteristics</b>               |               |  |                          |      |           |            |         |
| Gate Resistance                                | $R_g$         | $V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$              | -                        | 1.6  | -         | $\Omega$   |         |
| Total Gate Charge                              | $Q_g$         | $V_{GS} = 4.5V, V_{DS} = 15V, I_D = 15A$                 | -                        | 31.6 | -         | nC         |         |
| Gate-Source Charge                             | $Q_{gs}$      |  | -                        | 8.6  | -         |            |         |
| Gate-Drain Charge                              | $Q_{gd}$      |  | -                        | 11.7 | -         |            |         |
| Turn-On Delay Time                             | $t_{d(on)}$   | $V_{GS} = 10V, V_{DD} = 15V, R_G = 3.3\Omega, I_D = 15A$ | -                        | 9    | -         | nS         |         |
| Rise Time                                      | $t_r$         |  | -                        | 19   | -         |            |         |
| Turn-Off Delay Time                            | $t_{d(off)}$  |  | -                        | 58   | -         |            |         |
| Fall Time                                      | $t_f$         |  | -                        | 15.2 | -         |            |         |
| <b>Drain-Source Body Diode Characteristics</b> |               |  |                          |      |           |            |         |
| Diode Forward Voltage <sup>2</sup>             | $V_{SD}$      | $I_S = 1A, V_{GS} = 0V$                                  | -                        | -    | 1.0       | V          |         |
| Continuous Source Current <sup>1,5</sup>       | $I_S$         | $V_G = V_D = 0V, \text{Force Current}$                   | -                        | -    | 96        | A          |         |
| Body Diode Reverse Recovery Time               | $t_{rr}$      | $I_F = 30A, di/dt = 100A/\mu s$                          | -                        | 18   | -         | nS         |         |
| Body Diode Reverse Recovery Charge             | $Q_{rr}$      |  | -                        | 8    | -         | nC         |         |

## Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1\text{mH}, I_{AS} = 53.8A$
- The power dissipation is limited by 175 $^\circ\text{C}$  junction temperature
- The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

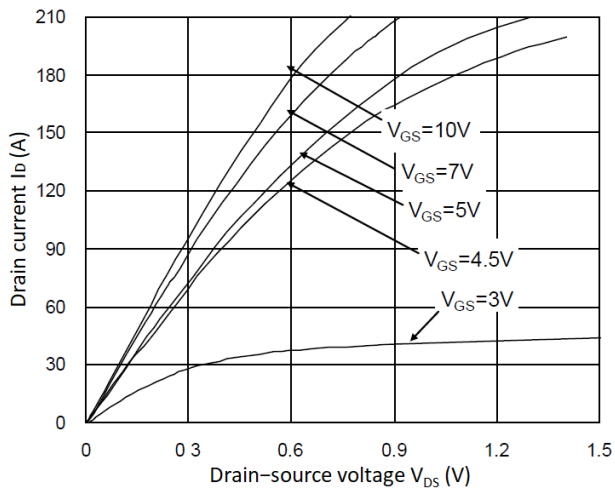


Figure 1. Output Characteristics

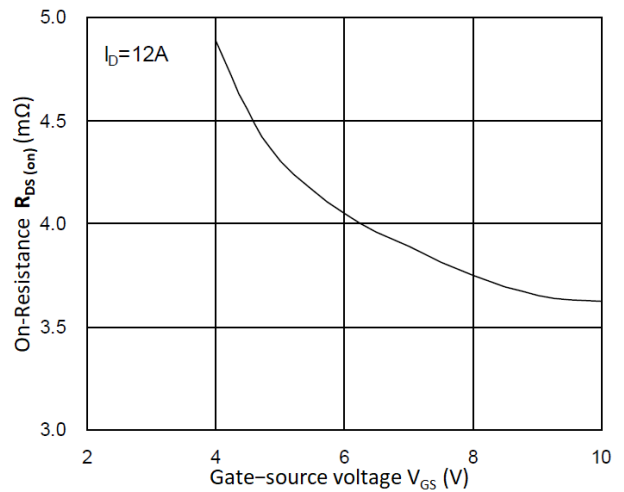


Figure 2.  $R_{DS(on)}$  vs.  $V_{GS}$

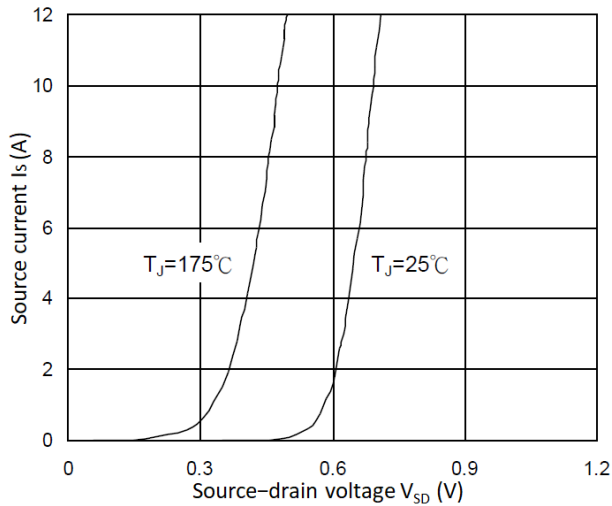


Figure 3. Forward Characteristics of Reverse

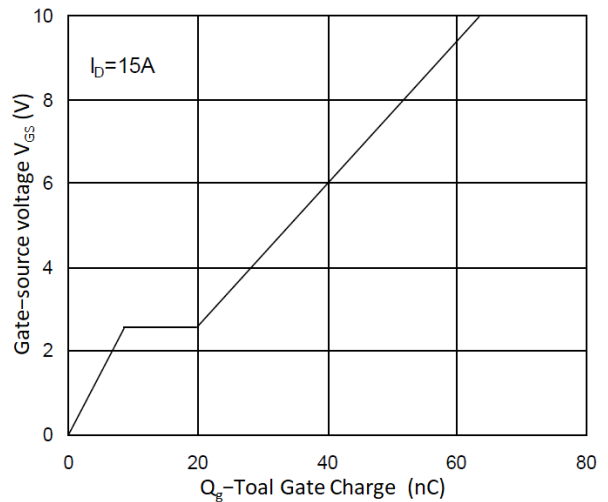


Figure 4. Gate Charge Characteristics

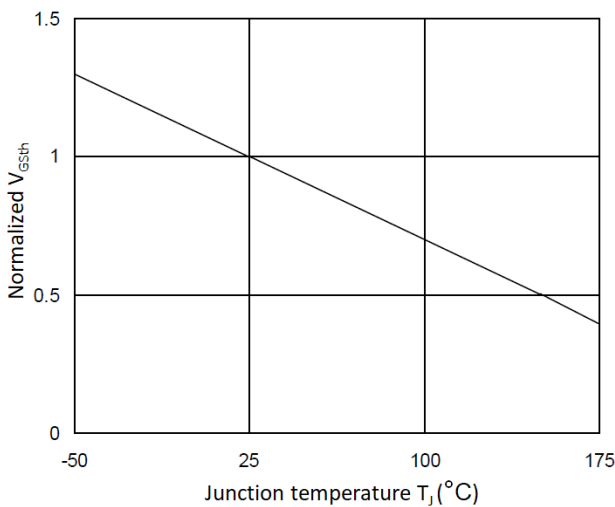


Figure 5. Normalized  $V_{GS(th)}$  vs.  $T_J$

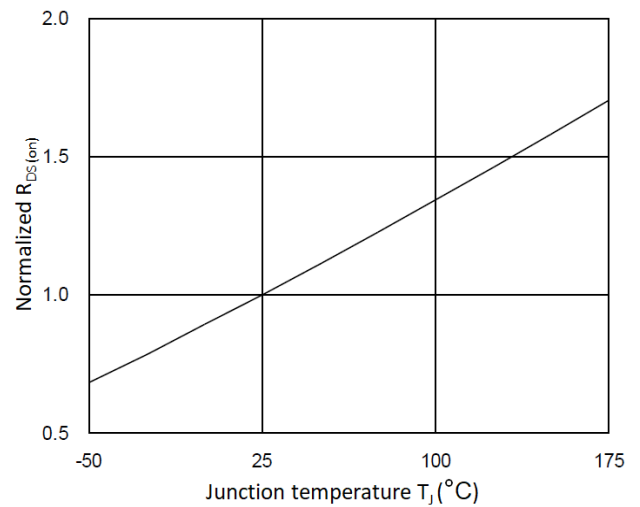


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

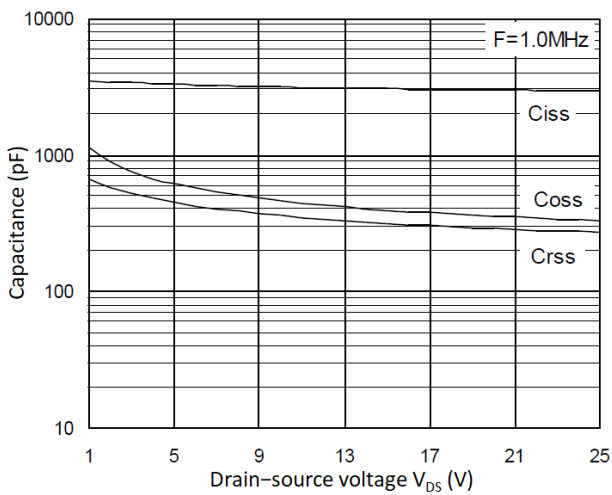


Figure 7. Capacitance Characteristics

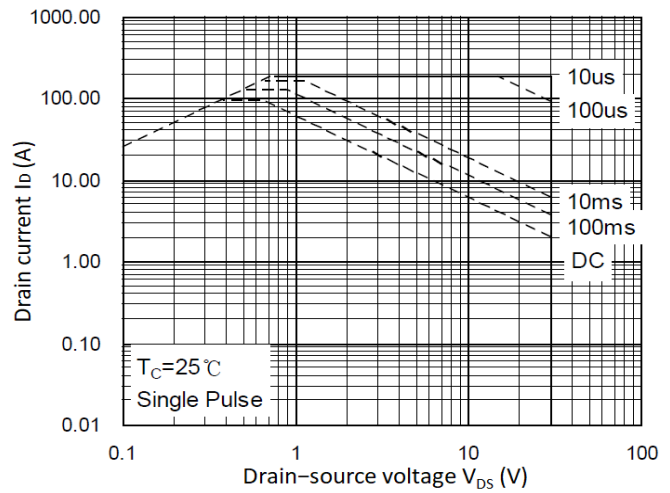


Figure 8. Safe Operating Area

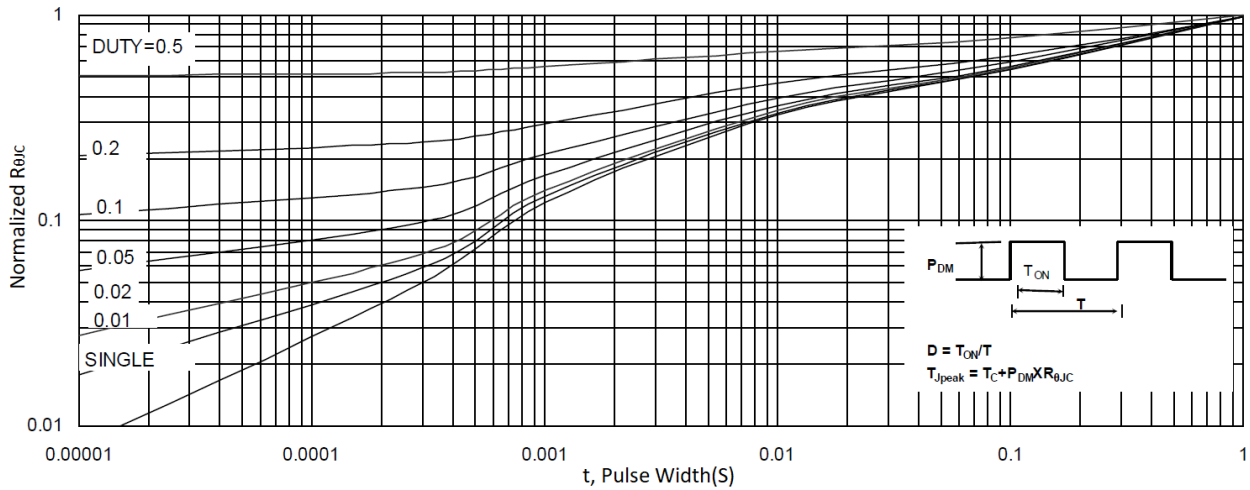


Figure 9. Normalized Maximum Transient Thermal Impedance

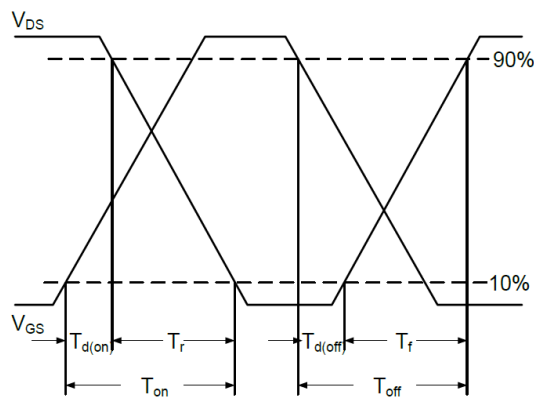


Figure 10. Switching Time Waveform

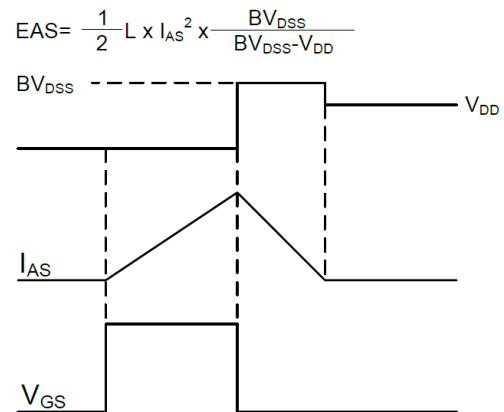
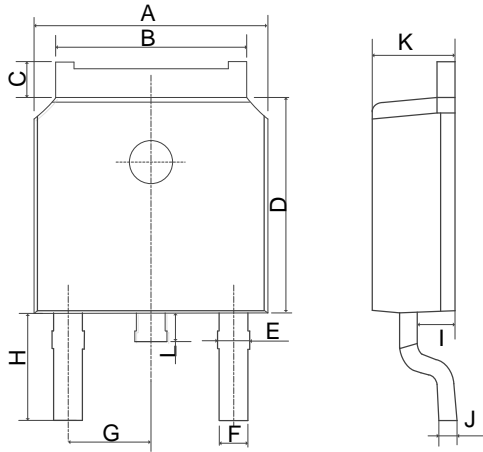


Figure 11. Unclamped Inductive Switching Waveform

## Mechanical Dimensions for TO-252

## COMMON DIMENSIONS

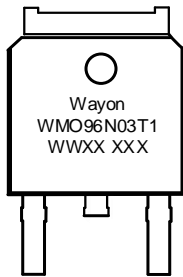


| SYMBOL | MM      |      |
|--------|---------|------|
|        | MIN     | MAX  |
| A      | 6.40    | 6.80 |
| B      | 5.13    | 5.50 |
| C      | 0.88    | 1.28 |
| D      | 5.90    | 6.22 |
| E      | 0.68    | 1.10 |
| F      | 0.68    | 0.91 |
| G      | 2.29REF |      |
| H      | 2.90REF |      |
| I      | 0.85    | 1.17 |
| J      | 0.51REF |      |
| K      | 2.10    | 2.50 |
| L      | 0.40    | 1.00 |

## Ordering Information

| Part       | Package | Marking    | Packing method |
|------------|---------|------------|----------------|
| WMO96N03T1 | TO-252  | WMO96N03T1 | Tape and Reel  |

## Marking Information



WMO96N03T1 = Device code

WWXX XXX= Manufacturing code

## Contact Information

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